

Surface Mount Superfast Recovery Rectifier

Reverse Voltage - 50 to 600 V

Forward Current - 3 A

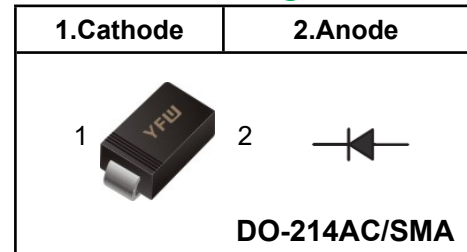
FEATURES

- ◆ Glass Passivated Chip Junction
- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Superfast reverse recovery time
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

- ◆ Case: DO-214AC/SMA
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.07g / 0.002oz

Pinning



Marking Code

ES3A	ES3A
ES3B	ES3B
ES3D	ES3D
ES3G	ES3G
ES3J	ES3J

Absolute Maximum Ratings and characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

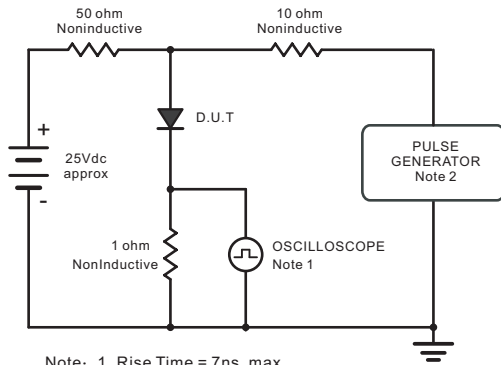
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	ES3A	ES3B	ES3D	ES3G	ES3J	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$	$I_{F(AV)}$	3					A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	80					A
Maximum Instantaneous Forward Voltage at 3 A	V_F	0.95			1.25	1.65	V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100					μA
Typical Junction Capacitance at $V_R = 4\text{V}, f = 1\text{MHz}$	C_j	40					pF
Maximum Reverse Recovery Time ⁽¹⁾	T_{rr}	35					nS
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA} / R_{\theta JC}$	50/16					$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150					$^\circ\text{C}$

(1) Measured with $I_F = 0.5\text{A}, I_R = 1\text{A}, I_n = 0.25\text{A}$

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.
Input Impedance = 1megohm, 22pF.
2. Rise Time = 10ns, max.
Source Impedance = 50 ohms.

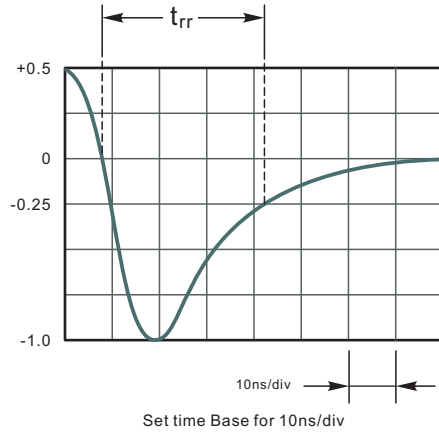


Fig.2 Maximum Average Forward Current Rating

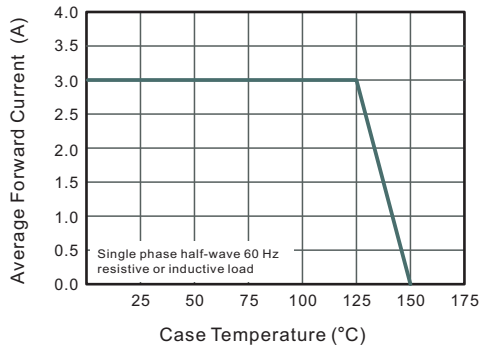


Fig.3 Typical Reverse Characteristics

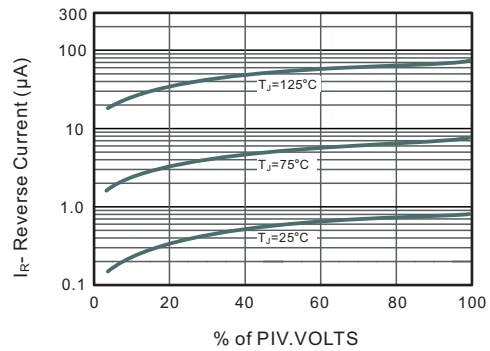


Fig.4 Typical Forward Characteristics

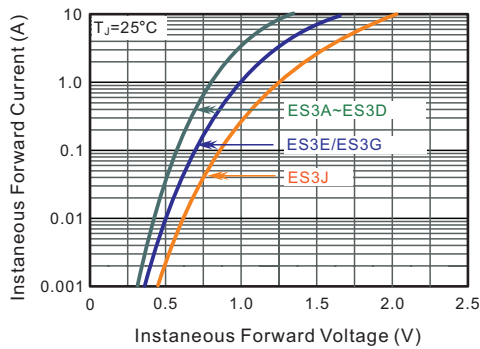


Fig.5 Typical Junction Capacitance

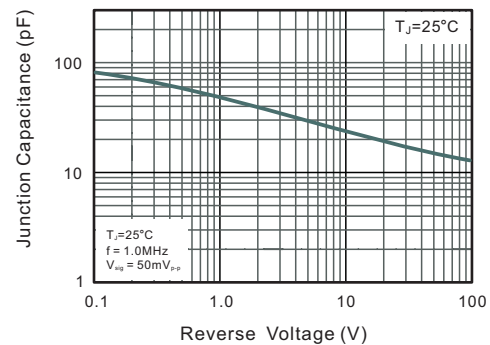


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

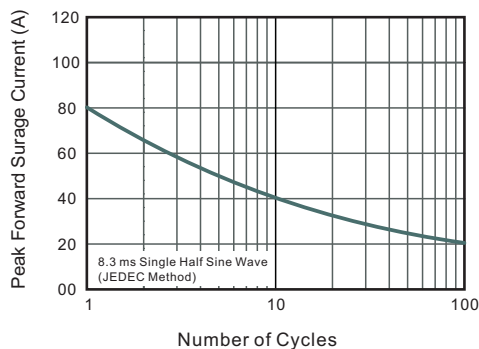
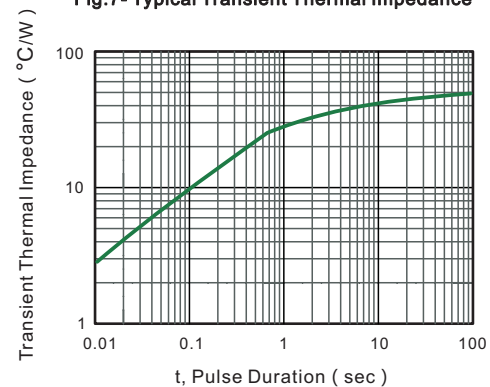


Fig.7- Typical Transient Thermal Impedance



Package Outline DO-214AC SMA

Plastic surface mounted package; 2 leads



UNIT		A	D	E	H _E	c	e	g	a
mm	max	2.42	4.5	2.80	5.2	0.31	1.6	1.5	0.3
	min	1.98	4.0	2.54	4.7	0.15	1.3	0.9	
mil	max	96	181	110	205	12	63	59	12
	min	78	157	100	185	6	51	35	

The recommended mounting pad size



Unit : $\frac{\text{mm}}{\text{(mil)}}$

Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
DO-214AC SMA	Tape/Reel, 11" reel	5000	EIA-481-1
	Tape/Reel, 7" reel	2000	EIA-481-1